

FP2636 (Frameless Version) Unpacking Instructions

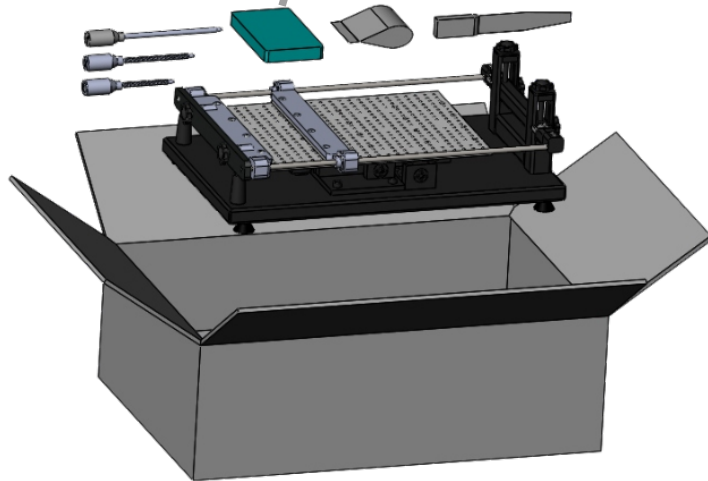
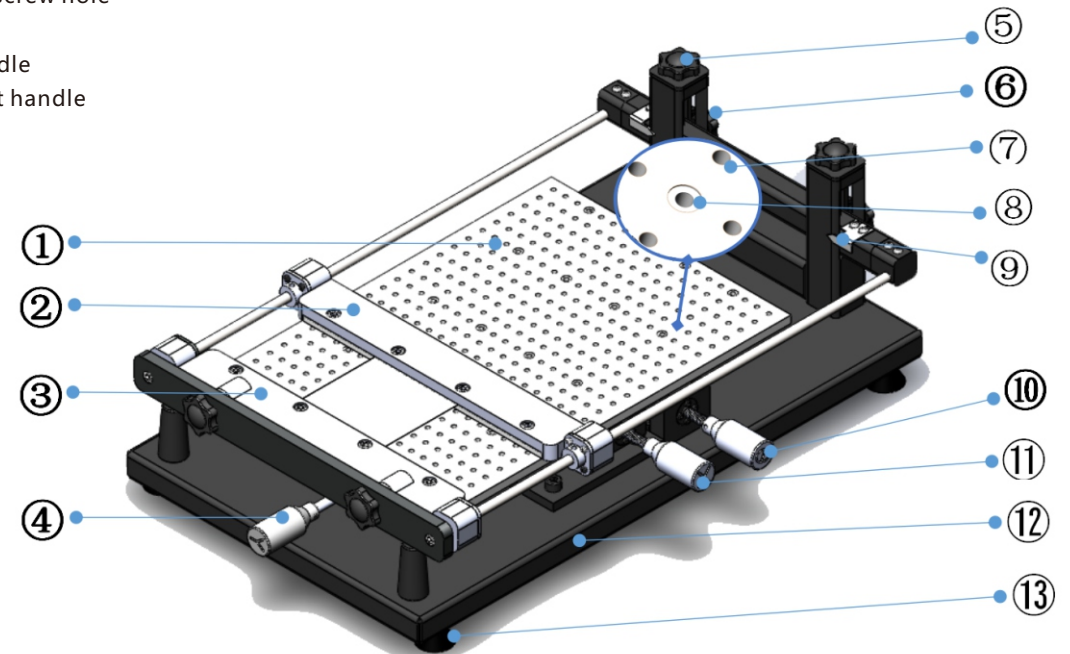
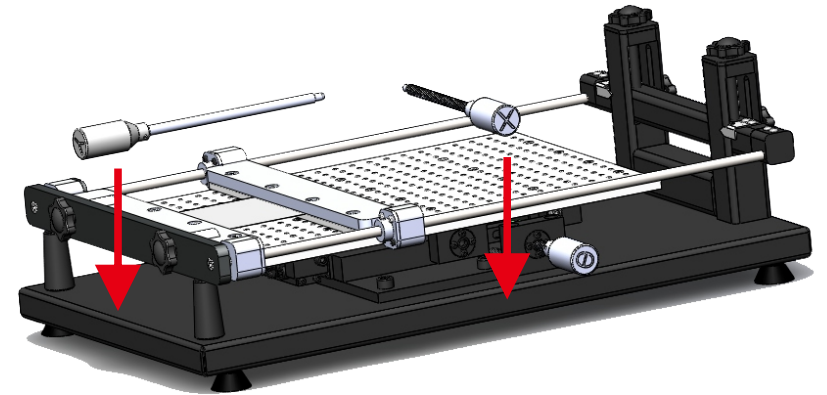
Accessories List



Install X,Y, θ handles to their positions accordingly.

FP2636 Parts list

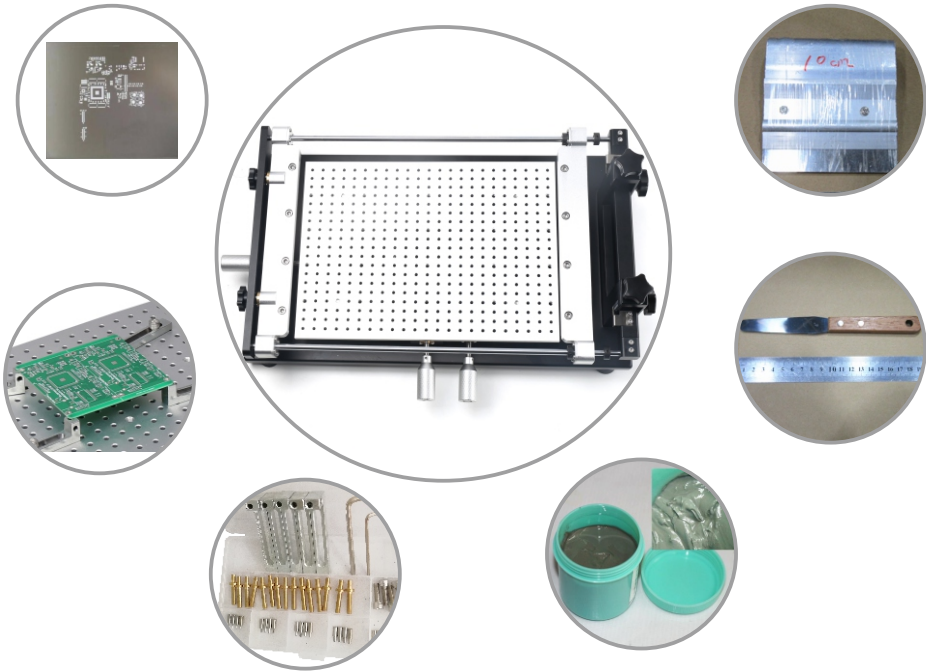
- ①: Porous positioning plate
- ②: Rear steel mesh fixed pressure plate
- ③: Front steel mesh fixed pressure plate
- ④: Y direction adjustment handle
- ⑤: Steel mesh height adjustment knob
- ⑥: Steel mesh height beam fixing knob
- ⑦: PCB top post placement hole
- ⑧: L-shaped fixing base screw hole
- ⑨: Height pointer
- ⑩: Angle adjustment handle
- ⑪: X direction adjustment handle
- ⑫: Printing table base
- ⑬: Printing table mats



FP2636 (Frameless Version) User Instructions

I. Preparation:

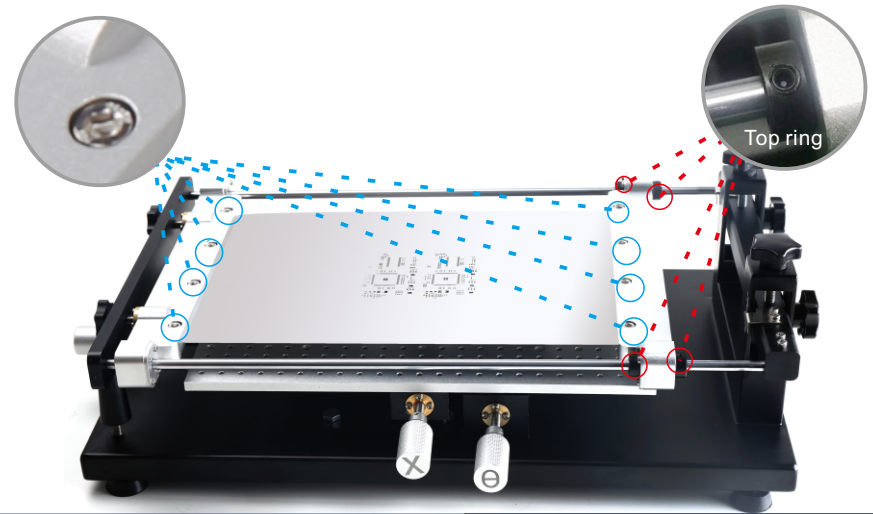
FP2636 stencil printer, frameless stencil, PCB, accessory box, solder paste, stirring knife, scraper blade



L-shaped seats 5Pcs | L-shaped wrenches 2Pcs | positioning pins: 1mm 4Pcs, 1.5mm 4Pcs, 2mm 4Pcs, 2.5mm 4Pcs, 3mm 4Pcs | PCB top post 15Pcs | Fixing screws 5Pcs

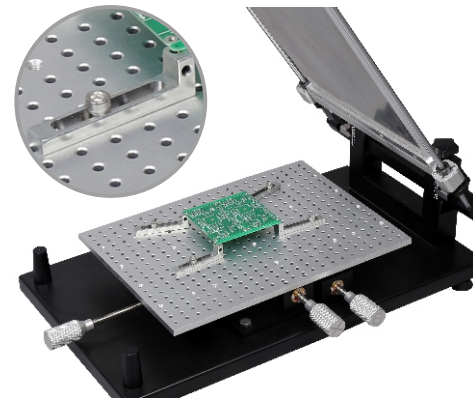
II. Install the frameless stencil:

Loosen the four "Set screw", adjust the "rear stencil fixing platen" to a suitable position, loosen the 8 screws on the front and rear stencil fixing platen, and put in the "frameless stencil", tighten the screws.



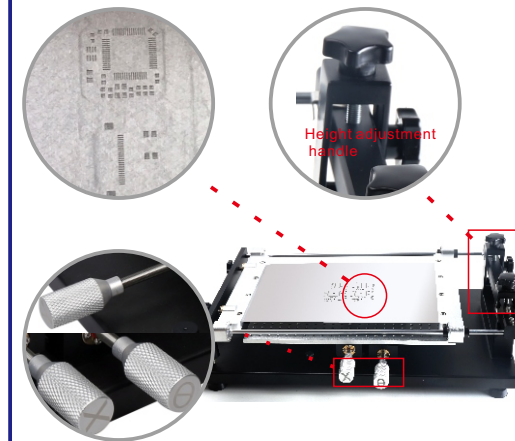
III. Place the PCB:

Install four "L-shaped seats" and "positioning pins" according to the actual positioning holes on the PCB (PS: Due to the limited XY adjustment range, the position of the "PCB" should be as close as possible to the hole location of the frameless stencil), if the PCB is easy to deform, you can install the PCB top post to the size of the PCB.



IV. Adjust the stencil:

Adjust the "height adjustment handle" to adjust the height of the stencil, adjust the x, y and angle adjustment handle to adjust the X/Y position.

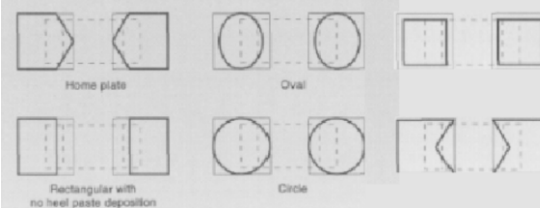


FP2636 (Frameless Version) Printing Process Instructions

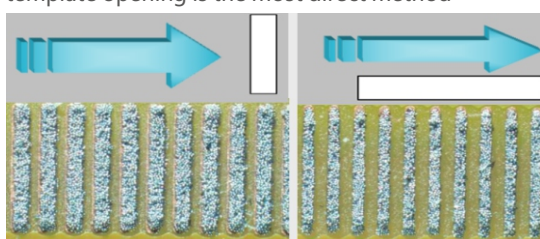
Process Processes:

Prepare materials → Adjust the stencil printer → Stir solder paste → Place solder paste → Place the PCB and close the Stencil → Printing solder paste → Clean the Stencil

Stencil for material preparation




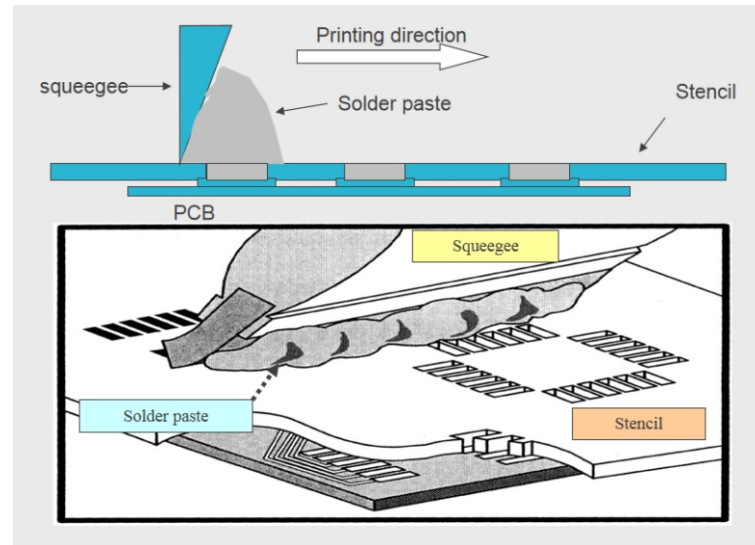
More and more micro components are used, how to take into account the amount of solder paste on large and small pads: Controlling the shape and size of the template opening is the most direct method



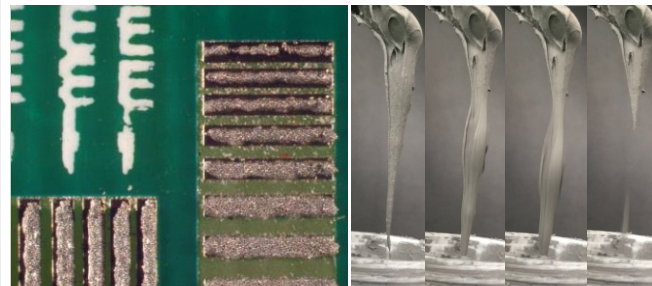
There is a big difference in the amount of solder paste in the parallel and vertical directions. When opening holes on the Stencil, the opening width in the parallel direction should be reduced accordingly.

Solder paste for material preparation

Unopened, reheated solder paste should be stored in the refrigerator when it is not used within 24 hours, the refrigeration temperature should be between 3°C and 8°C, do not reheat the solder paste of the same bottle more than twice. Before use, it must be taken out of the refrigerator and placed at room temperature for more than 4 hours before it can be opened for use.

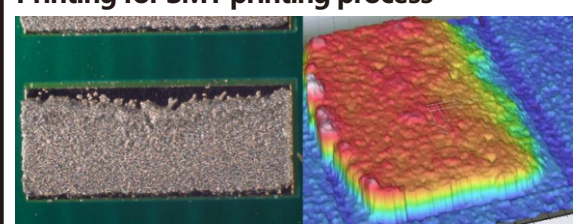
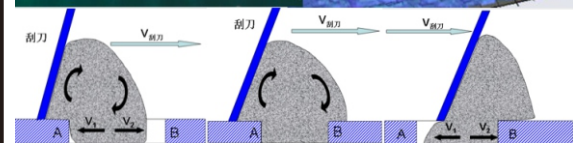



Solder paste for SMT printing process



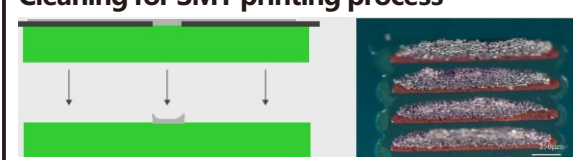
Before each addition the solder paste, the solder paste must be stirred uniformly before use, manual stirring speed is 2-3 seconds per revolution, in the same direction for 2 minutes to 5 minutes to make it into a fluid. The picture on the left is a typical printing abnormality caused by insufficient solder paste stirring. The picture on the right is a simple method for testing liquidity (Picking up solder paste with a stirring knife can naturally fall)

Printing for SMT printing process

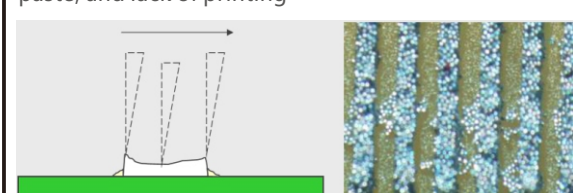



Solder paste does not roll, stencil holes filling is insufficient, solder paste is omission or defect.

Cleaning for SMT printing process



The surface of the stencil is not thoroughly brushed clean, the solder paste is poorly formed, less solder paste, and lack of printing



Contaminated, Causes defects such as tin beads; poor solder paste molding, increased cleaning frequency.